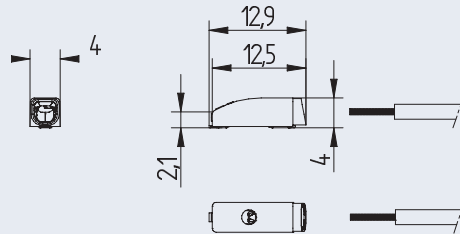
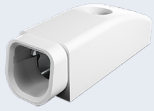


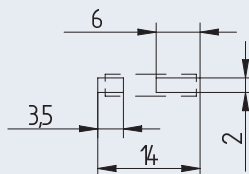
SMD Terminal blocks

46.131 · SMD Terminal block - MiniFlex



General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.

Recommended dimensions for solder tags



SMD-Terminal block - MiniFlex with push wire contacts and contact opening function

1 pole - 46.131.2001-0

Direct insertion of solid and stranded, tinned wire ends and finely stranded conductors by using the contact opening function

Contact opening function - also for release of already inserted wires

Mounting and wiring position: PCB top side

Machine-compatible "tape-and-reel" packaging

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: Housing: PPA, white
Contact material: CuNi
Contact surface: hot-dipped tinned

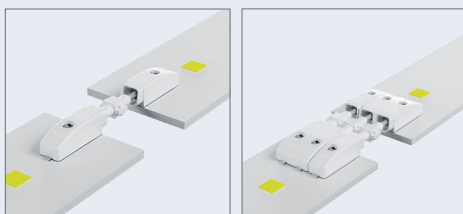
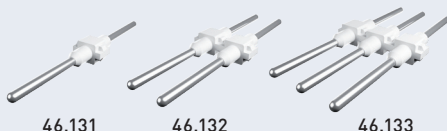
To operate the contact opening function, we recommend the use of our tools 46.131.U802-0 and 46.131.E397-1

Packaging data 46.131.2001-0	
Weight per piece	0.20 g
Pieces per reel	2.650 pcs
Diameter of tape-and-reel packaging	381 mm - (15")
Reel width	24 mm
Weight per reel	1.3 kg
Number of reels per cardboard	13 pcs
Number of SMD terminal blocks per cardboard	34.450 pcs
Weight per cardboard	15 kg
Dimensions cardboard (LxWxH)	400 x 405 x 415 mm



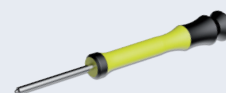
Accessories:

SMD Mini-Flex-B2B-connector. For connecting PCBs. Connectors are available in 26 mm (U701), 28 mm (U702) and 30 mm (U703) length.



Contact opening tool

For opening the contacts when using fine-stranded conductors or to remove already inserted conductors.



46.131.U802-0



46.131.E397-1

Integrated stripping function for wire ends cut but not stripped

Connection data	
Connection technology	Push wire contacts
Solid wires	0.20 - 0.75 mm ² , AWG 24-18
Stranded, tinned wires	0.20 - 0.5 mm ² , AWG 24-20
Stranded wires	0.20 - 0.75 mm ² , AWG 24-18
Strip length (ø < 2.1 mm)	8 +1 mm
Strip length (ø 2.1 - 2.7 mm)	9 +1 mm
Conductor entry angle to the PCB	0°
Wire release function by	Contact opening tool

Pull-out force according to DN 60999-1

0.2 mm ²	min. 10 N
0.34 mm ²	min. 15 N
0.5 mm ²	min. 20 N
0.75 mm ²	min. 30 N
Insertion force	max. 10 N

Geometrical data

Pin spacing	4 mm / 0.16 inch
Width	4 mm / 0.16 inch
Height	4 mm / 0.16 inch
Depth	12.9 mm / 0.51 inch

Material data

Insulating material group	I
Insulating material	PPA, white
PTI	600
Flammability class, based on UL 94	V-0
Contact material	CuNi
Contact surface	hot-dipped tinned

Mechanical data

Mounting position	PCB top side
Mounting type	Lead-free reflow soldering

Temperature data

Marginal temperatures	-70 °C to + 150 °C
Ambient temperature	-70 °C to + 125 °C
T-classification according to IEC 60998-1 para. 12	120° C

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1)

Rated voltage (III / 3)	63 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	160 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	320 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to UL 1977 / CSA-C22.2 No. 182.3

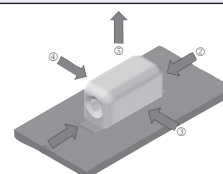
Rated voltage	600 V
Rated current	USR 9 A, AWG 24 -18 CNR 6 A, AWG 24-20 CNR 9 A, AWG 18

Country specific certificates

VDE / ENEC	EN IEC 60947-7-4 File no.: 40040866
cURus	UL 1977 / CSA-C22.2 No. 182.3 File no.: E-365006

Shear forces according to IEC 62137-1-2.

These values are maximum values that apply only for impuls, not for continuous load.

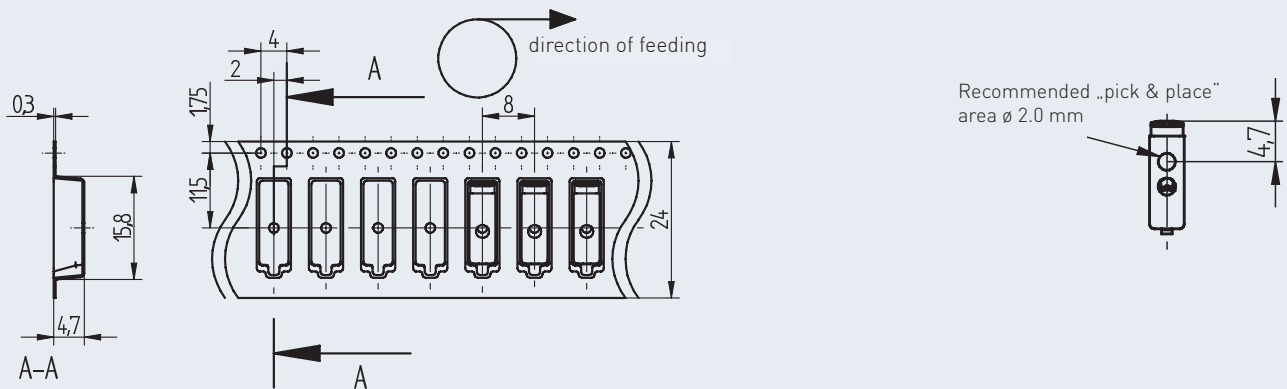


Direction 1 + 2 shear force along	50 N
Direction 3 + 4 shear force across	20 N
Direction 5 pull-off force	20 N

Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C. Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	Reflow-profile (lead-free)
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150 µm)